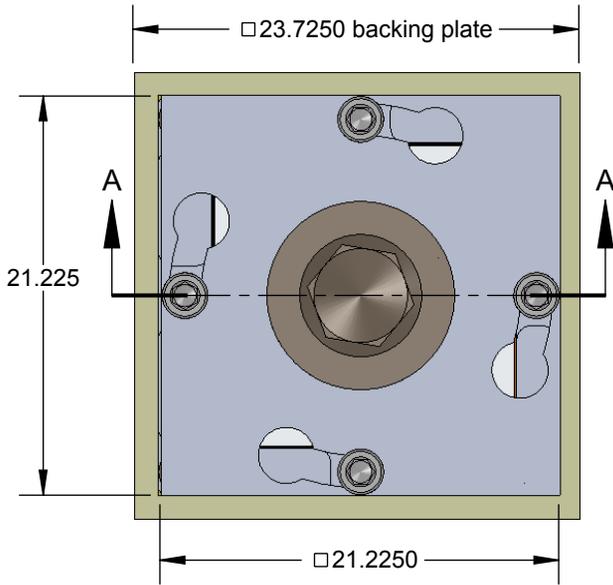


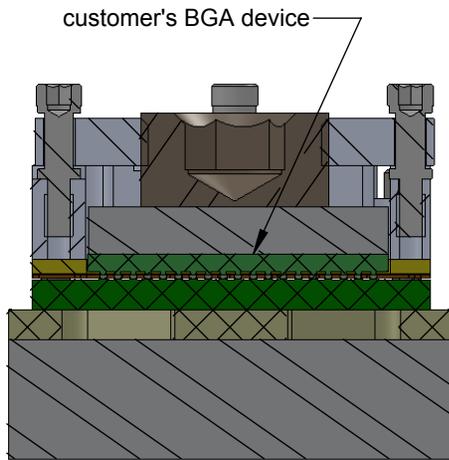
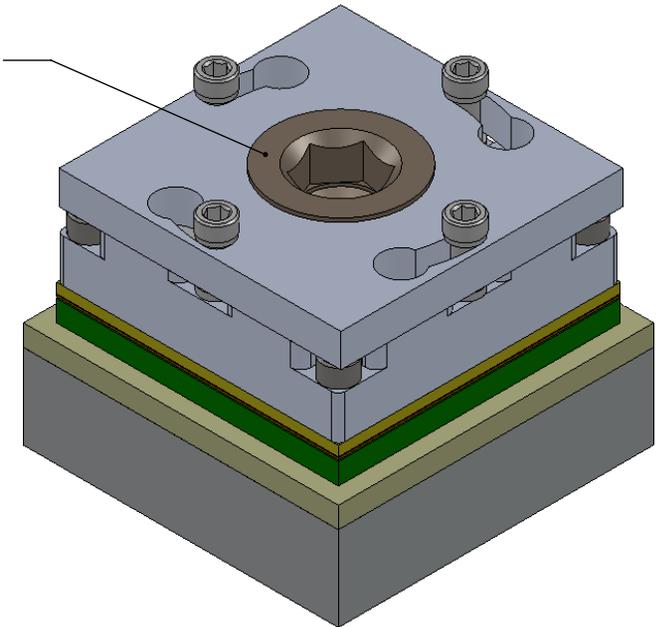
# Silver Button (GT) BGA Socket - Direct mount, solderless

## Features

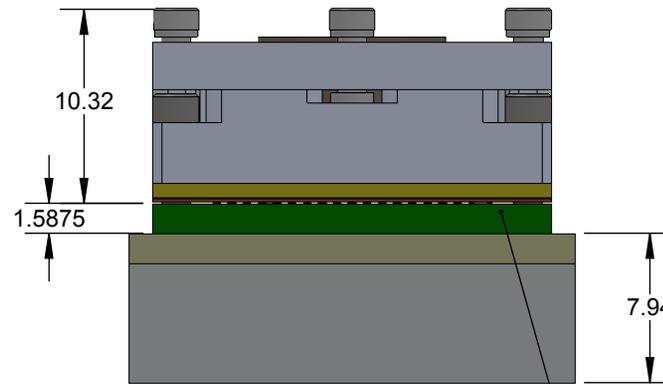
- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Recommended torque 4-4.5 in lb.



SECTION A-A



customer's target board

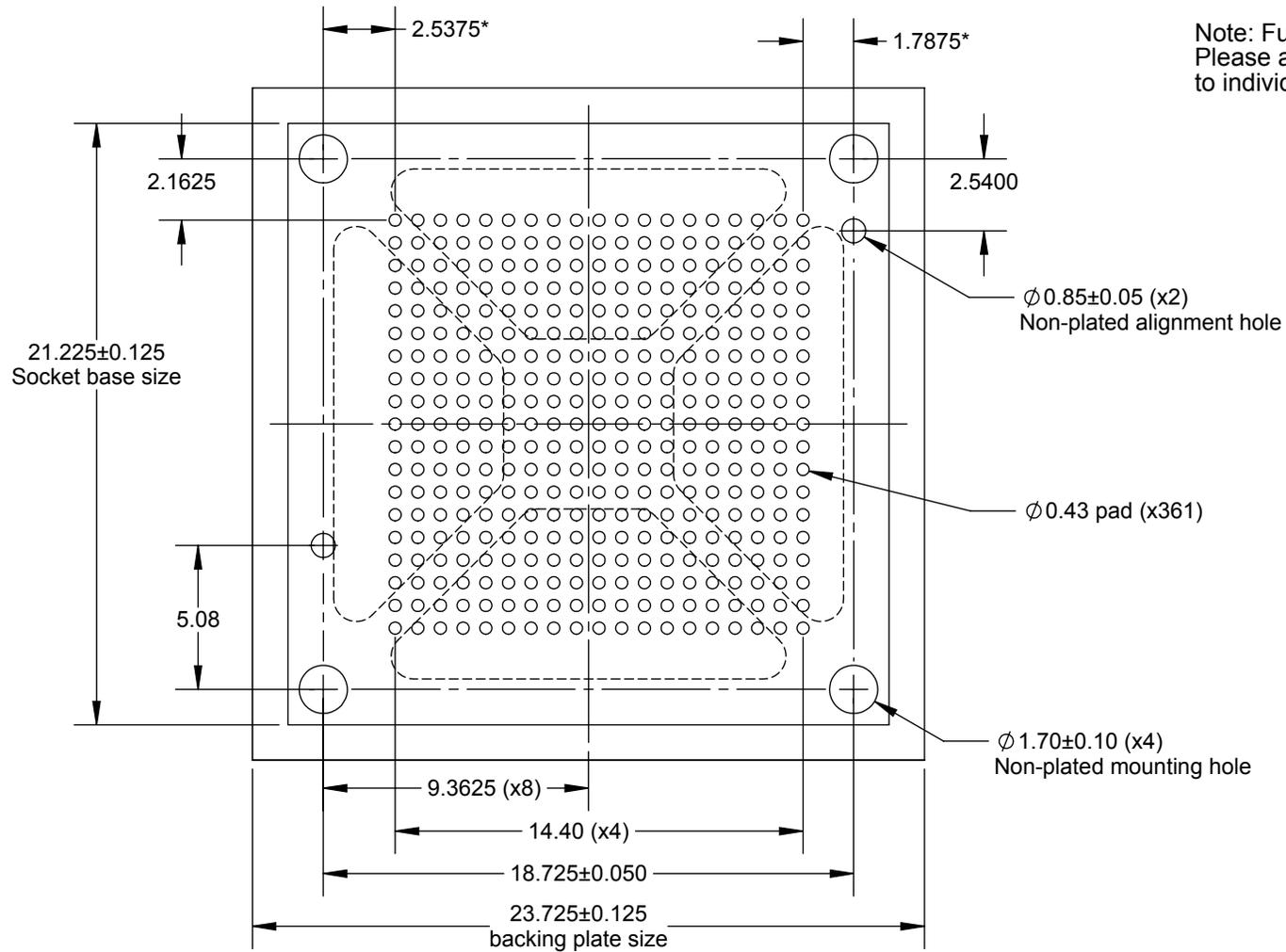
## Description: GT-BGA for BGA361 0.8mm pitch 16mm x16mm package

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters  $\pm 0.0254\text{mm}$  [ $\pm 0.001$ "]. Pitches (from true position)  $\pm 0.0762\text{mm}$  [ $\pm 0.003$ "], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.127\text{mm}$  [ $\pm 0.005$ "] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p><b>GT-BGA-2020 Drawing</b> ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: N/A Finish: N/A Weight: 20.62</p>	<p>STATUS: Released ENG: S. Huang FILE: GT-BGA-2020 Dwg</p>	<p>SHEET: 1 OF 4 DRAWN BY: M. Raske DATE: 03/18/2015</p>	<p>REV. A SCALE: 2.5:1</p>
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Note: BGA pattern is not symmetrical with respect to the mounting holes.



Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

### Target PCB Recommendations

Total thickness: 1.6mm min.

Plating: Gold or Solder finish

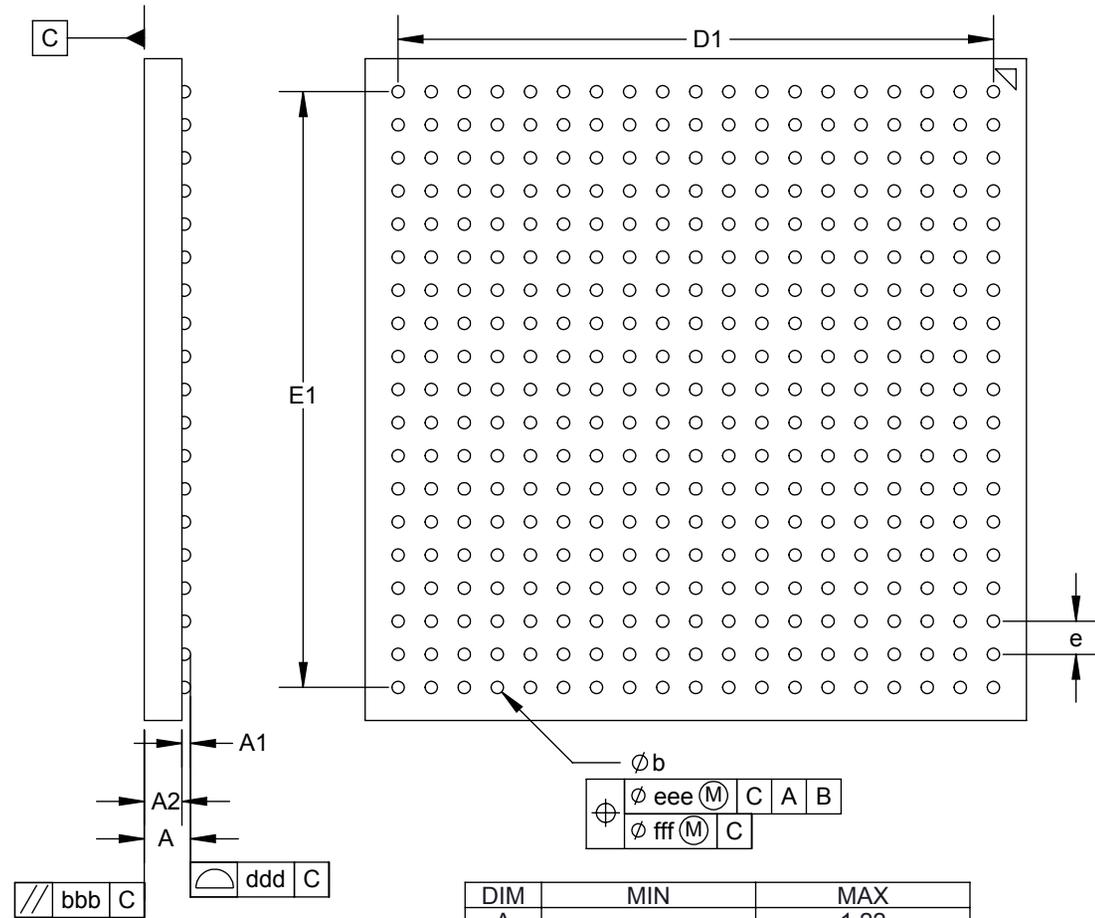
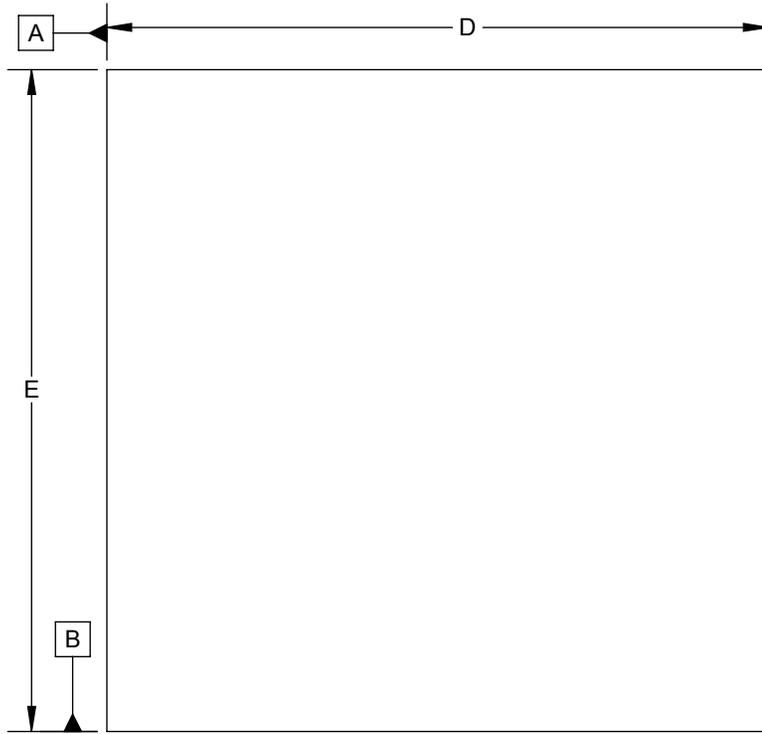
PCB Pad height: Same or higher than solder mask

### Description: Recommended PCB layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters  $\pm 0.0254\text{mm}$  [ $\pm 0.001"$ ], Pitches (from true position)  $\pm 0.0762\text{mm}$  [ $\pm 0.003"$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.127\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

 <b>GT-BGA-2020 Drawing</b> ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 20.62	STATUS: Released	SHEET: 2 OF 4	REV. A
		ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 4:1
		FILE: GT-BGA-2020 Dwg	DATE: 03/18/2015	



Dimensions are in millimeters.

1. Interpret dimensions and tolerances per ASME Y14.5M-1994.
2. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
3. Datum C (seating plane) is defined by the spherical crowns of the solder balls.
4. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A	-	1.22
A1	0.16	0.26
A2	0.86	0.96
b	0.25	0.35
D	16.00	
D1	14.40	
E	16.00	
E1	14.40	
e	0.80	
aaa	0.15	
bbb	0.20	
ddd	0.08	
eee	0.15	
fff	0.05	

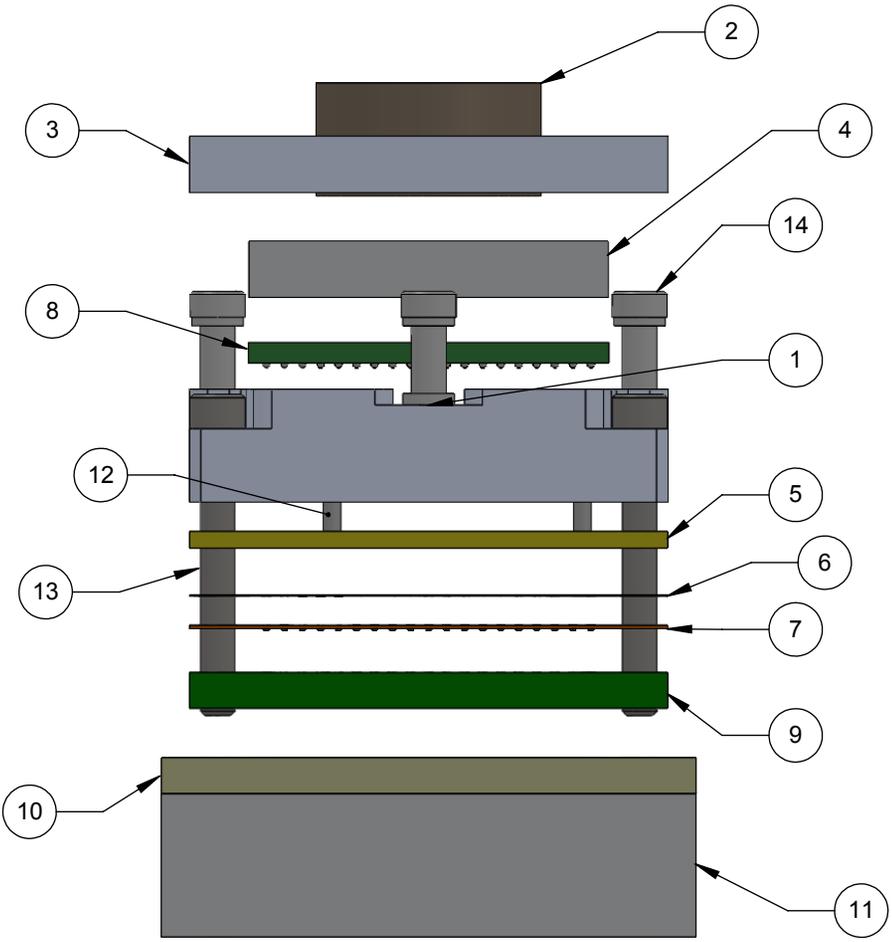
### Description: Compatible Device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

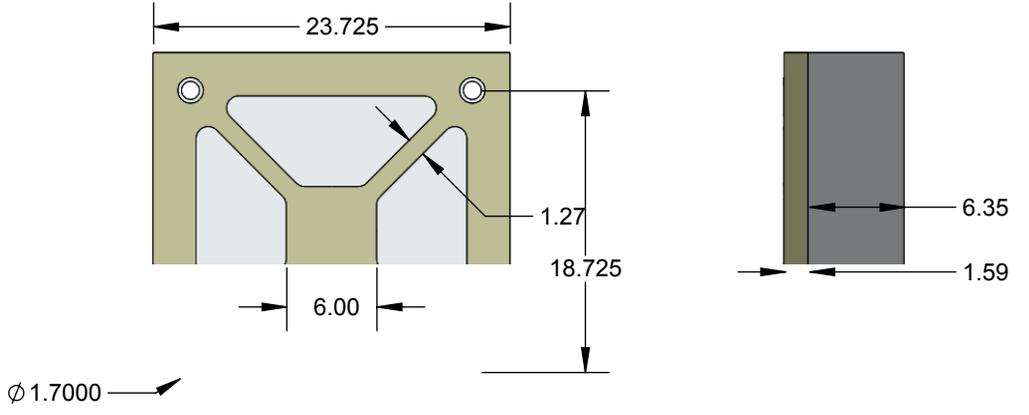
Tolerances: Hole diameters  $\pm 0.0254\text{mm}$  [ $\pm 0.001"$ ], Pitches (from true position)  $\pm 0.0762\text{mm}$  [ $\pm 0.003"$ ], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.127\text{mm}$  [ $\pm 0.005"$ ] unless stated otherwise. Materials and specifications are subject to change without notice.

19 x 19 array

 <p><b>GT-BGA-2020 Drawing</b> ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: N/A Finish: N/A Weight: 20.62</p>	<p>STATUS: Released ENG: S. Huang FILE: GT-BGA-2020 Dwg</p>	<p>SHEET: 3 OF 4 DRAWN BY: M. Raske DATE: 03/18/2015</p>	<p>REV. A SCALE: 5.5:1</p>
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ITEM NO.	DESCRIPTION	Material
1	Socket Base	7075-T6 Aluminum Alloy
2	Compression Screw M10	7075-T6 Alumium Alloy
3	Socket Lid	7075-T6 Aluminum Alloy
4	Compression Plate	7075-T6 Aluminum Alloy
5	IC Guide 16mm IC	Torlon 4203
6	Ball Guide 16mm IC 0.8mm pitch 19x19 array	Kapton Polyimide/Cirlex
7	GT Elastomer 16x16mm IC 0.8mm pitch 19x19 array	Conductive Elastomer
8	Test Chip 16mm IC 0.8mm pitch 19x19 array	FR4 High temp
9	Customer's target PCB for 16x16mm, 19x19 0.8mm pitch BGA	FR4 Standard
10	Insulation Plate 16x16mm IC	FR4 High temp
11	Backing Plate	7075-T6 Alumium Alloy
12	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
13	#0-80 x 0.5, SH Cap Screw	Alloy Steel
14	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)



Insulation plate and backing plate detail

**Description: Skt, Backing Plate Detail**

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.  
 Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <b>GT-BGA-2020 Drawing</b> ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A	STATUS: Released	SHEET: 4 OF 4	REV. A
	Finish: N/A	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:1
	Weight: 20.62	FILE: GT-BGA-2020 Dwg	DATE: 03/18/2015	